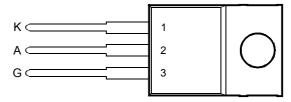
- 5 A Continuous On-State Current
- 30 A Surge-Current
- Glass Passivated Wafer
- 400 V to 800 V Off-State Voltage
- Max I_{GT} of 200 μA

TO-220 PACKAGE (TOP VIEW)



Pin 2 is in electrical contact with the mounting base.

MDC1ACA

absolute maximum ratings over operating case temperature (unless otherwise noted)

RATING	SYMBOL	VALUE	UNIT	
	TIC106D		400	
Repetitive peak off-state voltage (see Note 1)	TIC106M	V	600	V
	TIC106S	V _{DRM}	700	V
	TIC106N		800	
	TIC106D		400	
Repetitive peak reverse voltage	TIC106M	V	600	V
nepetitive peak reverse voltage	TIC106S	V _{RRM}	700	
	TIC106N		800	
Continuous on-state current at (or below) 80°C case temperature (see Note 2)	I _{T(RMS)}	5	Α	
Average on-state current (180° conduction angle) at (or below) 80°C case temperature			3.2	Α
(see Note 3)			5.2	^
Surge on-state current (see Note 4)			30	Α
Peak positive gate current (pulse width ≤ 300 μs)			0.2	Α
Peak gate power dissipation (pulse width ≤ 300 μs)			1.3	W
Average gate power dissipation (see Note 5)	P _{GM} P _{G(AV)}	0.3	W	
Operating case temperature range	T _C	-40 to +110	°C	
Storage temperature range	T _{stg}	-40 to +125	°C	
Lead temperature 1.6 mm from case for 10 seconds	T _L	230	°C	

- NOTES: 1. These values apply when the gate-cathode resistance R_{GK} = 1 k Ω .
 - 2. These values apply for continuous dc operation with resistive load. Above 80°C derate linearly to zero at 110°C.
 - 3. This value may be applied continuously under single phase 50 Hz half-sine-wave operation with resistive load. Above 80°C derate linearly to zero at 110°C.
 - 4. This value applies for one 50 Hz half-sine-wave when the device is operating at (or below) the rated value of peak reverse voltage and on-state current. Surge may be repeated after the device has returned to original thermal equilibrium.
 - 5. This value applies for a maximum averaging time of 20 ms.



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electrical characteristics at 25°C case temperature (unless otherwise noted)

PARAMETER			TEST CONDITION	ONS	MIN			UNIT
I _{DRM}	Repetitive peak off-state current	V _D = rated V _{DRM}	R _{GK} = 1 kΩ	T _C = 110°C			400	μΑ
I _{RRM}	Repetitive peak reverse current	V _R = rated V _{RRM}	I _G = 0	T _C = 110°C			1	mA
I _{GT}	Gate trigger current	V _{AA} = 6 V	$R_L = 100 \Omega$	t _{p(g)} ≥ 20 μs		60	200	μΑ
		$V_{AA} = 6 V$ $t_{p(g)} \ge 20 \mu s$	$R_L = 100 \Omega$ $R_{GK} = 1 k\Omega$	T _C = - 40°C			1.2	
V _{GT}	Gate trigger voltage	$V_{AA} = 6 V$ $t_{p(g)} \ge 20 \mu s$	$R_L = 100 \Omega$ $R_{GK} = 1 k\Omega$		0.4 0.6	1	V	
		$V_{AA} = 6 \text{ V}$ $t_{p(g)} \ge 20 \mu\text{s}$	$R_L = 100 \Omega$ $R_{GK} = 1 k\Omega$	T _C = 110°C	0.2			
I _H	Holding current	$V_{AA} = 6 \text{ V}$ Initiating $I_T = 10 \text{ mA}$	$R_{GK} = 1 k\Omega$	T _C = - 40°C			8	mA
		$V_{AA} = 6 \text{ V}$ Initiating $I_T = 10 \text{ mA}$	$R_{GK} = 1 k\Omega$				5	ША
V _{TM}	Peak on-state voltage	I _{TM} = 5 A	(See Note 6)				1.7	V
dv/dt	Critical rate of rise of off-state voltage	V _D = rated V _D	R _{GK} = 1 kΩ	T _C = 110°C		10		V/µs

NOTE 6: This parameter must be measured using pulse techniques, t_p = 300 µs, duty cycle ≤ 2 %. Voltage sensing-contacts, separate from the current carrying contacts, are located within 3.2 mm from the device body.

thermal characteristics

PARAMETER			TYP	MAX	UNIT
$R_{\theta JC}$	Junction to case thermal resistance			3.5	°C/W
$R_{\theta JA}$	Junction to free air thermal resistance			62.5	°C/W

resistive-load-switching characteristics at 25°C case temperature

	PARAMETER	TEST CONDITIONS			MIN	TYP	MAX	UNIT
t _{gt}	Gate-controlled turn-on time	I _T = 5 A	I _G = 10 mA	See Figure 1		1.75		μs
tq	Circuit-commutated turn-off time	I _T = 5 A I _{RM} = 8 A	I _G = 10 mA	See Figure 2		7.7		μs

PARAMETER MEASUREMENT INFORMATION

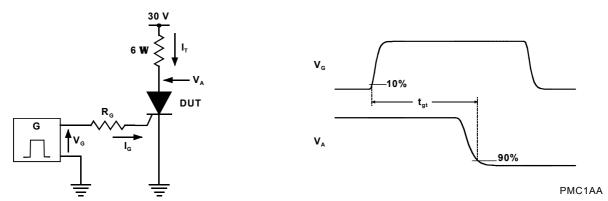
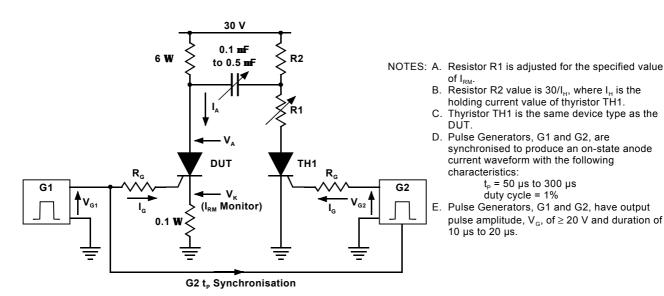


Figure 1. Gate-controlled turn-on time



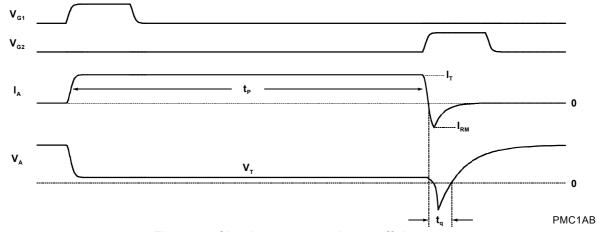
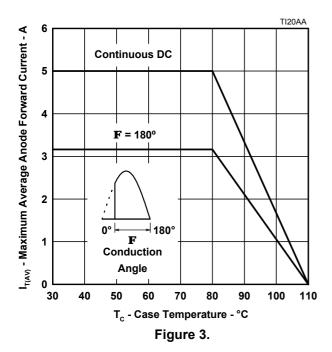


Figure 2. Circuit-commutated turn-off time



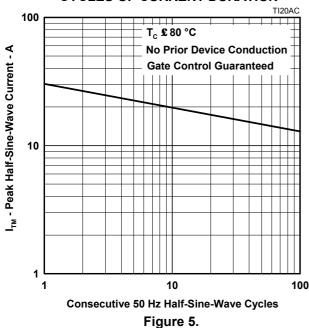
TYPICAL CHARACTERISTICS

AVERAGE ANODE ON-STATE CURRENT DERATING CURVE



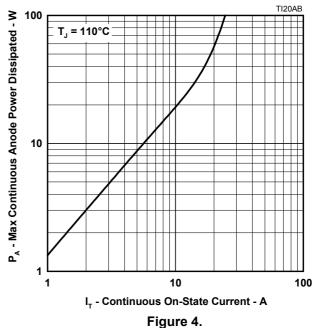
SURGE ON-STATE CURRENT

CYCLES OF CURRENT DURATION

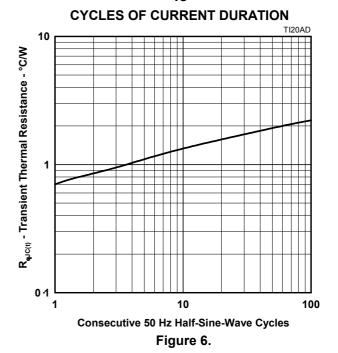


MAX CONTINUOUS ANODE POWER DISSIPATED vs

CONTINUOUS ON-STATE CURRENT



TRANSIENT THERMAL RESISTANCE



PRODUCT INFORMATION

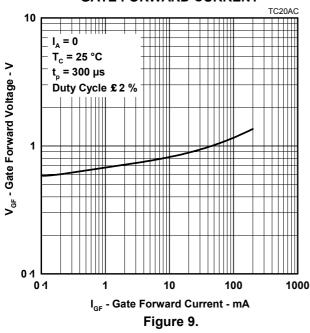
TYPICAL CHARACTERISTICS

GATE TRIGGER CURRENT vs

CASE TEMPERATURE TC20AA $V_{AA} = 6 V$ R_L = 100 W _{ет} - Gate Trigger Current - µA t_{p(g)} ³ 20 μs 100 10 -50 -25 75 100 125 T_c - Case Temperature - °C Figure 7.

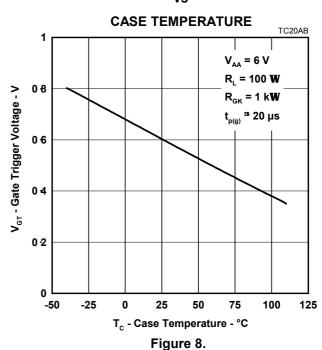
GATE FORWARD VOLTAGE VS

GATE FORWARD CURRENT

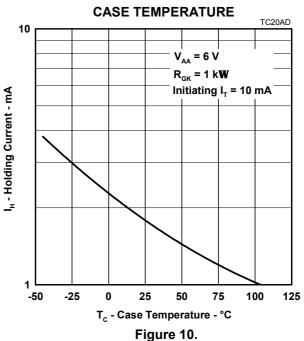


PRODUCT

GATE TRIGGER VOLTAGE vs



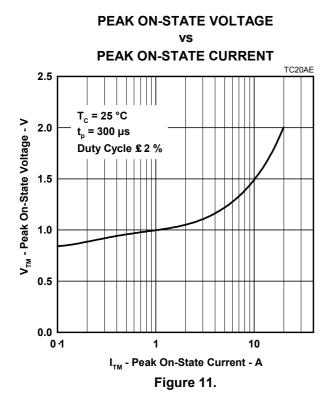
HOLDING CURRENT vs

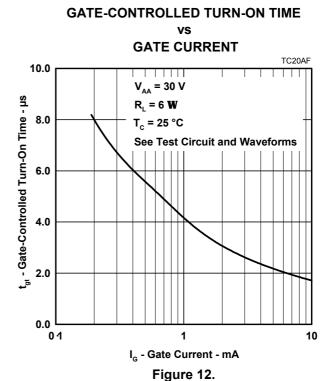


INFORMATION

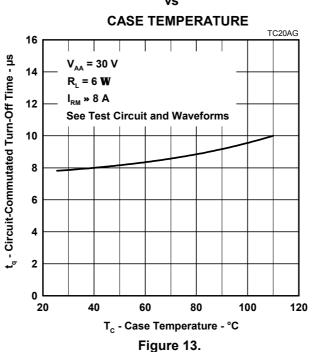


TYPICAL CHARACTERISTICS





CIRCUIT-COMMUTATED TURN-OFF TIME vs



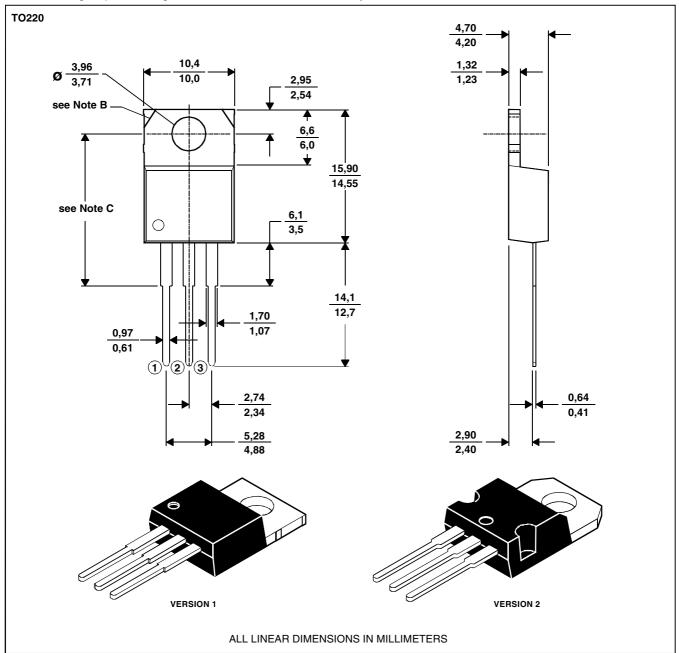
PRODUCT INFORMATION

MECHANICAL DATA

TO-220

3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



NOTES: A. The centre pin is in electrical contact with the mounting tab.

B. Mounting tab corner profile according to package version.

C. Typical fixing hole centre stand off height according to package version. Version 1, 18.0 mm. Version 2, 17.6 mm. MDXXBE



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